

Darlington Complementary Silicon Power Transistors

TIP140, TIP141, TIP142, (NPN); TIP145, TIP146, TIP147, (PNP)

Designed for general-purpose amplifier and low frequency switching applications.

Features

- High DC Current Gain –
 $\text{Min } h_{FE} = 1000 @ I_C = 5.0 \text{ A, } V_{CE} = 4 \text{ V}$
- Collector–Emitter Sustaining Voltage – @ 30 mA
 $V_{CEO(sus)} = 60 \text{ Vdc (Min) – TIP140, TIP145}$
 $= 80 \text{ Vdc (Min) – TIP141, TIP146}$
 $= 100 \text{ Vdc (Min) – TIP142, TIP147}$
- Monolithic Construction with Built–In Base–Emitter Shunt Resistor
- These are Pb–Free Devices*

MAXIMUM RATINGS

Symbol	Rating	TIP140 TIP145	TIP141 TIP146	TIP142 TIP147	Unit
V_{CEO}	Collector – Emitter Voltage	60	80	100	Vdc
V_{CB}	Collector – Base Voltage	60	80	100	Vdc
V_{EB}	Emitter – Base Voltage	5.0			Vdc
I_C	Collector Current – Continuous – Peak (Note 1)	10 15			Adc
I_B	Base Current – Continuous	0.5			Adc
P_D	Total Power Dissipation @ $T_C = 25^\circ\text{C}$	125			W
T_J, T_{stg}	Operating and Storage Junction Temperature Range	–65 to +150			$^\circ\text{C}$

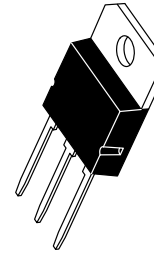
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

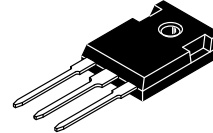
Symbol	Characteristic	Max	Unit
$R_{\theta JC}$	Thermal Resistance, Junction–to–Case	1.0	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance, Junction–to–Ambient	35.7	$^\circ\text{C/W}$

1. 5 ms, $\leq 10\%$ Duty Cycle.

*For additional information on our Pb–Free strategy and soldering details, please download the [onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D](#).



SOT–93 (TO–218)
CASE 340D
STYLE 1



TO–247
CASE 340L
STYLE 3

NOTE: Effective June 2012 this device will be available only in the TO–247 package. Reference FPCN# 16827.

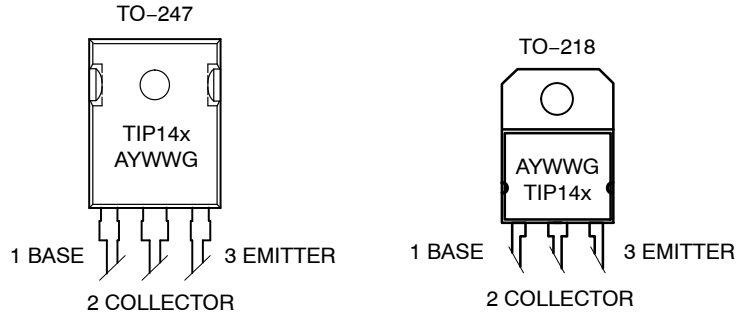
**10 AMPERE
 DARLINGTON
 COMPLEMENTARY SILICON
 POWER TRANSISTORS
 60–100 VOLTS, 125 WATTS**

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 8 of this data sheet.

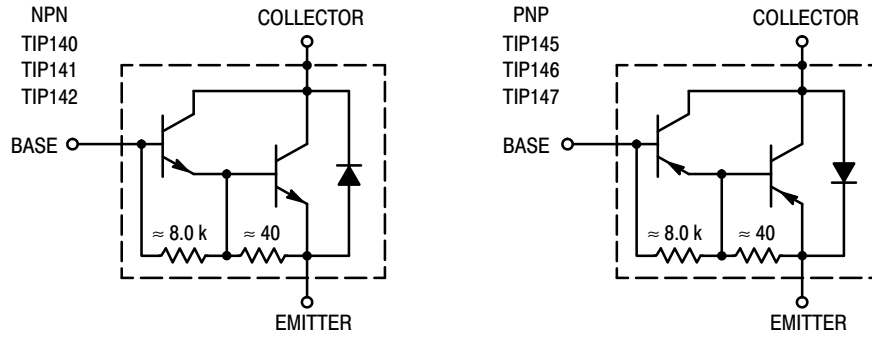
TIP140, TIP141, TIP142, (NPN); TIP145, TIP146, TIP147, (PNP)

MARKING DIAGRAMS



TIP14x = Device Code
 A = Assembly Location
 Y = Year
 WW = Work Week
 G = Pb-Free Package

DARLINGTON SCHEMATICS



TIP140, TIP141, TIP142, (NPN); TIP145, TIP146, TIP147, (PNP)

ELECTRICAL CHARACTERISTICS ($T_C = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Characteristic	Min	Typ	Max	Unit
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OFF CHARACTERISTICS

$V_{CEO(sus)}$	Collector–Emitter Sustaining Voltage (Note 2) ($I_C = 30\text{ mA}$, $I_B = 0$)	TIP140, TIP145	60	–	–	Vdc
		TIP141, TIP146	80	–	–	
		TIP142, TIP147	100	–	–	
I_{CEO}	Collector Cutoff Current ($V_{CE} = 30\text{ Vdc}$, $I_B = 0$) ($V_{CE} = 40\text{ Vdc}$, $I_B = 0$) ($V_{CE} = 50\text{ Vdc}$, $I_B = 0$)	TIP140, TIP145	–	–	2.0	mA
		TIP141, TIP146	–	–	2.0	
		TIP142, TIP147	–	–	2.0	
I_{CBO}	Collector Cutoff Current ($V_{CB} = 60\text{ V}$, $I_E = 0$) ($V_{CB} = 80\text{ V}$, $I_E = 0$) ($V_{CB} = 100\text{ V}$, $I_E = 0$)	TIP140, TIP145	–	–	1.0	mA
		TIP141, TIP146	–	–	1.0	
		TIP142, TIP147	–	–	1.0	
I_{EBO}	Emitter Cutoff Current ($V_{BE} = 5.0\text{ V}$)	–	–	2.0	mA	

ON CHARACTERISTICS (Note 2)

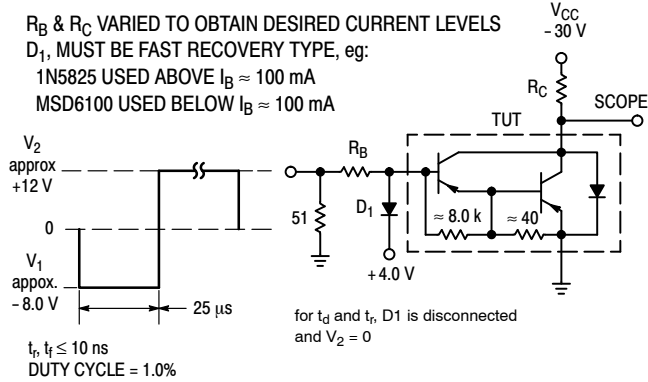
h_{FE}	DC Current Gain ($I_C = 5.0\text{ A}$, $V_{CE} = 4.0\text{ V}$) ($I_C = 10\text{ A}$, $V_{CE} = 4.0\text{ V}$)	1000	–	–	–
		500	–	–	
$V_{CE(sat)}$	Collector–Emitter Saturation Voltage ($I_C = 5.0\text{ A}$, $I_B = 10\text{ mA}$) ($I_C = 10\text{ A}$, $I_B = 40\text{ mA}$)	–	–	2.0	Vdc
		–	–	3.0	
$V_{BE(sat)}$	Base–Emitter Saturation Voltage ($I_C = 10\text{ A}$, $I_B = 40\text{ mA}$)	–	–	3.5	Vdc
$V_{BE(on)}$	Base–Emitter On Voltage ($I_C = 10\text{ A}$, $V_{CE} = 4.0\text{ Vdc}$)	–	–	3.0	Vdc

SWITCHING CHARACTERISTICS

Resistive Load (See Figure 1)	Resistive Load (See Figure 1)					
t_d	Delay Time	($V_{CC} = 30\text{ V}$, $I_C = 5.0\text{ A}$, $I_B = 20\text{ mA}$, Duty Cycle $\leq 2.0\%$, $I_{B1} = I_{B2}$, R_C & R_B Varied, $T_J = 25^\circ\text{C}$)	–	0.15	–	μs
t_r	Rise Time		–	0.55	–	μs
t_s	Storage Time		–	2.5	–	μs
t_f	Fall Time		–	2.5	–	μs

2. Pulse Test: Pulse Width = 300 μs , Duty Cycle $\leq 2.0\%$.

TIP140, TIP141, TIP142, (NPN); TIP145, TIP146, TIP147, (PNP)



For NPN test circuit reverse diode and voltage polarities.

Figure 1. Switching Times Test Circuit

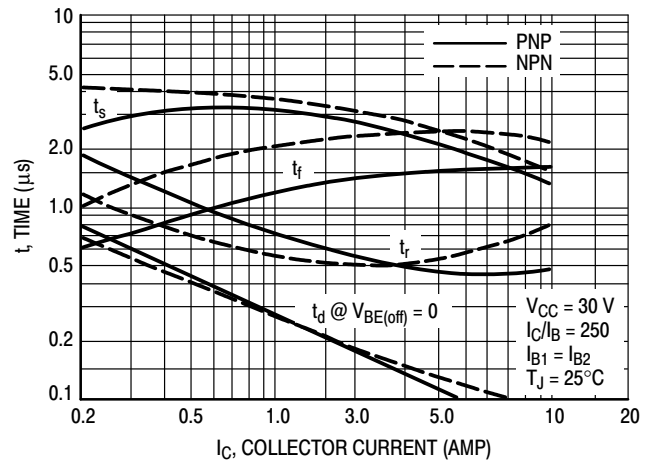


Figure 2. Switching Times

TIP140, TIP141, TIP142, (NPN); TIP145, TIP146, TIP147, (PNP)

TYPICAL CHARACTERISTICS

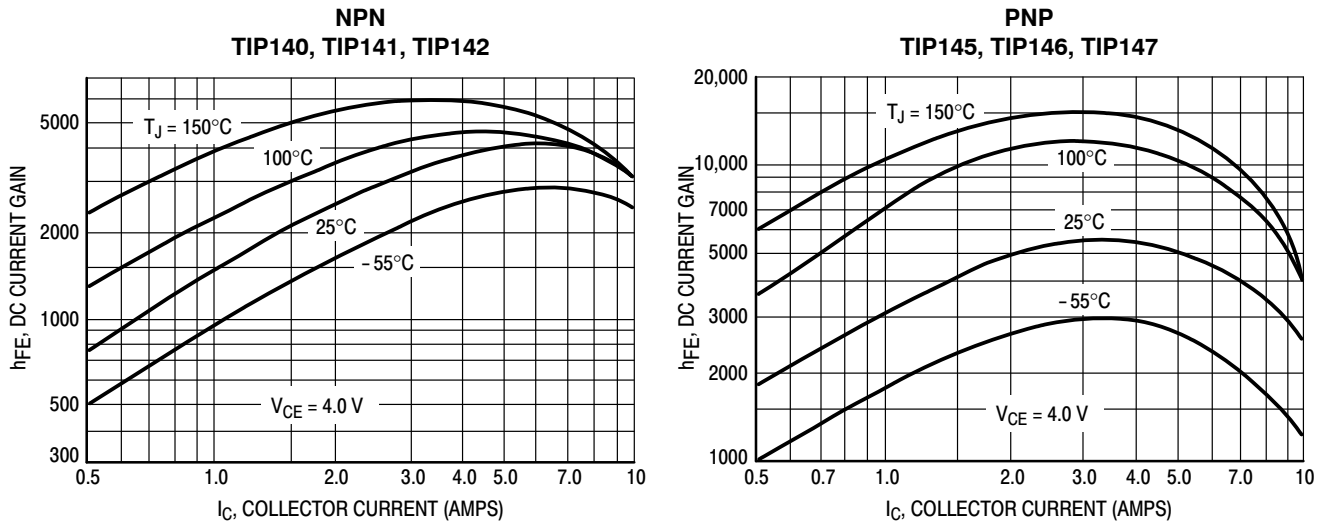


Figure 3. DC Current Gain versus Collector Current

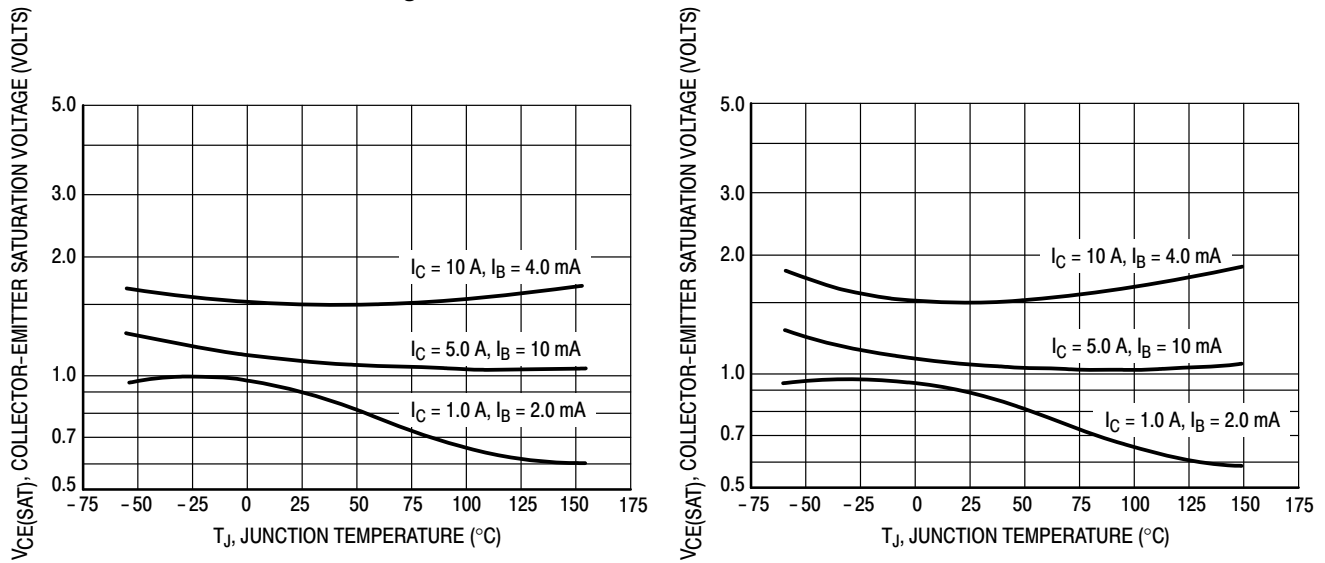


Figure 4. Collector-Emitter Saturation Voltage

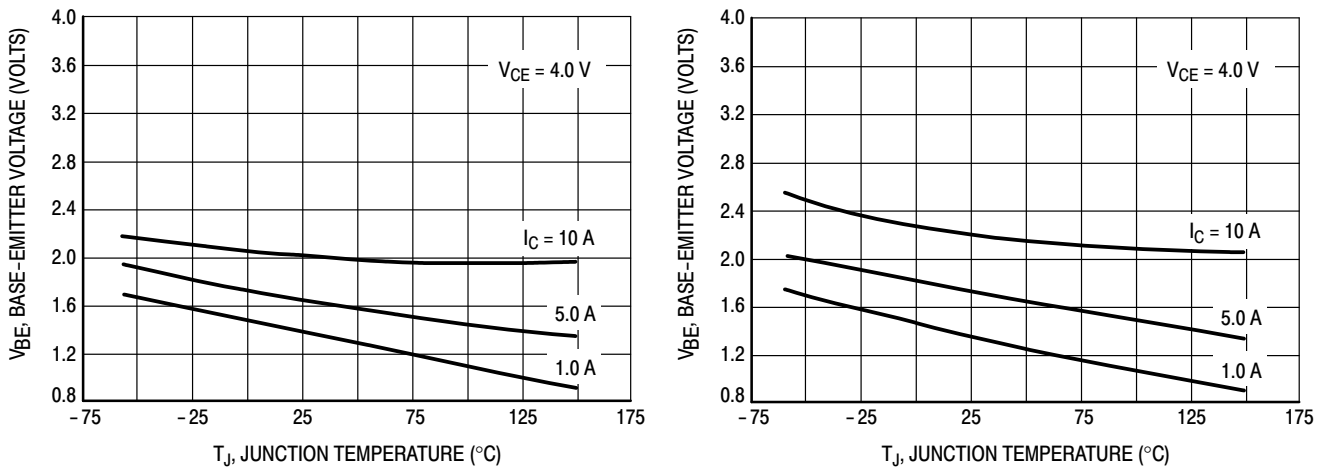


Figure 5. Base-Emitter Voltage

TIP140, TIP141, TIP142, (NPN); TIP145, TIP146, TIP147, (PNP)

ACTIVE-REGION SAFE OPERATING AREA

There are two limitations on the power handling ability of a transistor: average junction temperature and second breakdown. Safe operating area curves indicate $I_C - V_{CE}$ limits of the transistor that must be observed for reliable operation; i.e., the transistor must not be subjected to greater dissipation than the curves indicate.

The data of Figure 6 is based on $T_{J(pk)} = 150^\circ\text{C}$; T_C is variable depending on conditions. At high case temperatures, thermal limitations will reduce the power that can be handled to values less than the limitations imposed by second breakdown.

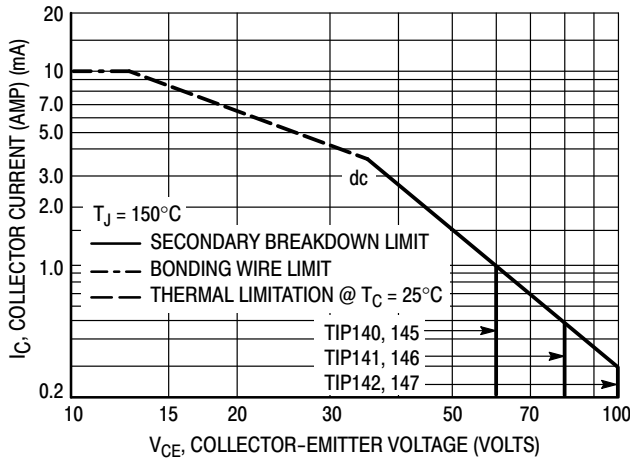


Figure 6. Active-Region Safe Operating Area

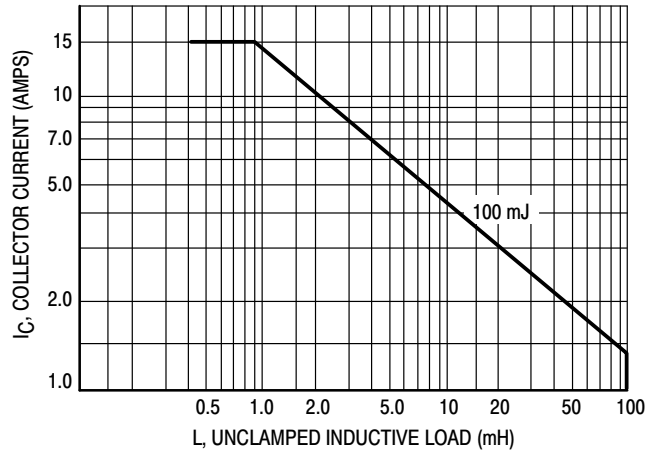
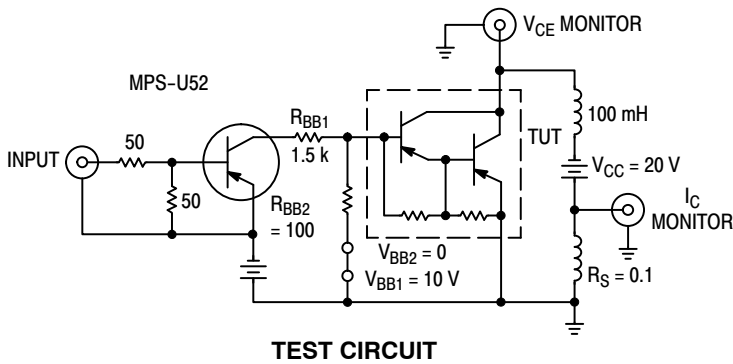
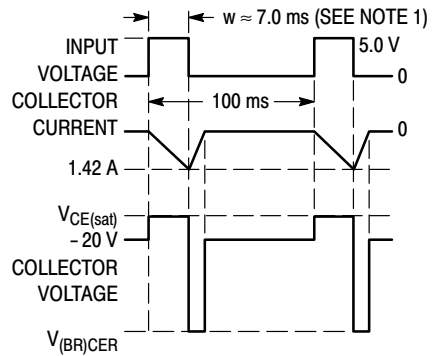


Figure 7. Unclamped Inductive Load



TEST CIRCUIT

NOTE 1: Input pulse width is increased until $I_{CM} = 1.42\text{ A}$.
NOTE 2: For NPN test circuit reverse polarities.



VOLTAGE AND CURRENT WAVEFORMS

Figure 8. Inductive Load

TIP140, TIP141, TIP142, (NPN); TIP145, TIP146, TIP147, (PNP)

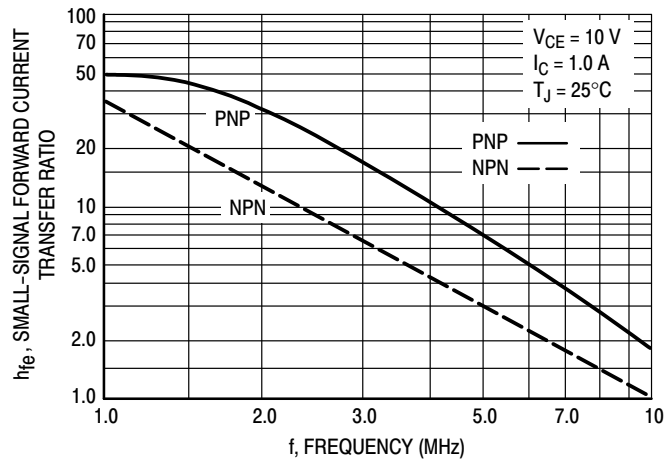


Figure 9. Magnitude of Common Emitter Small-Signal Short-Circuit Forward Current Transfer Ratio

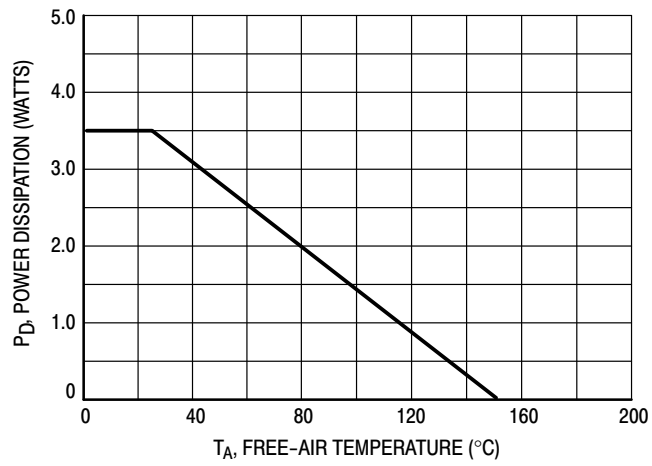


Figure 10. Free-Air Temperature Power Derating

TIP140, TIP141, TIP142, (NPN); TIP145, TIP146, TIP147, (PNP)

ORDERING INFORMATION

Device	Package	Shipping
TIP140G	SOT-93 (TO-218) (Pb-Free)	30 Units / Rail
TIP141G	SOT-93 (TO-218) (Pb-Free)	30 Units / Rail
TIP142G	SOT-93 (TO-218) (Pb-Free)	30 Units / Rail
TIP145G	SOT-93 (TO-218) (Pb-Free)	30 Units / Rail
TIP146G	SOT-93 (TO-218) (Pb-Free)	30 Units / Rail
TIP147G	SOT-93 (TO-218) (Pb-Free)	30 Units / Rail
TIP140G	TO-247 (Pb-Free)	30 Units / Rail
TIP141G	TO-247 (Pb-Free)	30 Units / Rail
TIP142G	TO-247 (Pb-Free)	30 Units / Rail
TIP145G	TO-247 (Pb-Free)	30 Units / Rail
TIP146G	TO-247 (Pb-Free)	30 Units / Rail
TIP147G	TO-247 (Pb-Free)	30 Units / Rail

MECHANICAL CASE OUTLINE

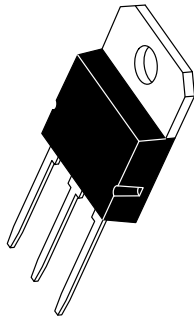
PACKAGE DIMENSIONS

ON Semiconductor®

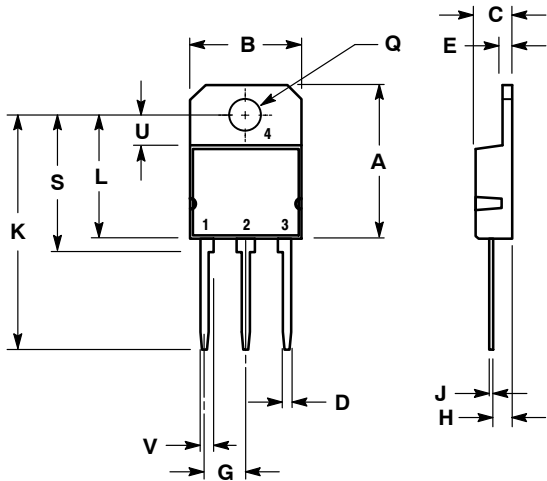


SOT-93 (TO-218) CASE 340D-02 ISSUE E

DATE 01/03/2002



SCALE 1:1



STYLE 1:
PIN 1. BASE
2. COLLECTOR
3. EMITTER
4. COLLECTOR

STYLE 2:
PIN 1. ANODE
2. CATHODE
3. ANODE
4. CATHODE

- NOTES:
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 - CONTROLLING DIMENSION: MILLIMETER.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	---	20.35	---	0.801
B	14.70	15.20	0.579	0.598
C	4.70	4.90	0.185	0.193
D	1.10	1.30	0.043	0.051
E	1.17	1.37	0.046	0.054
G	5.40	5.55	0.213	0.219
H	2.00	3.00	0.079	0.118
J	0.50	0.78	0.020	0.031
K	31.00 REF		1.220 REF	
L	---	16.20	---	0.638
Q	4.00	4.10	0.158	0.161
S	17.80	18.20	0.701	0.717
U	4.00 REF		0.157 REF	
V	1.75 REF		0.069	

MARKING DIAGRAM

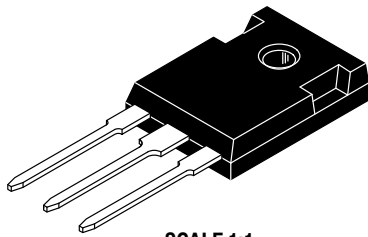


A = Assembly Location
Y = Year
WW = Work Week
xxxxx = Device Code

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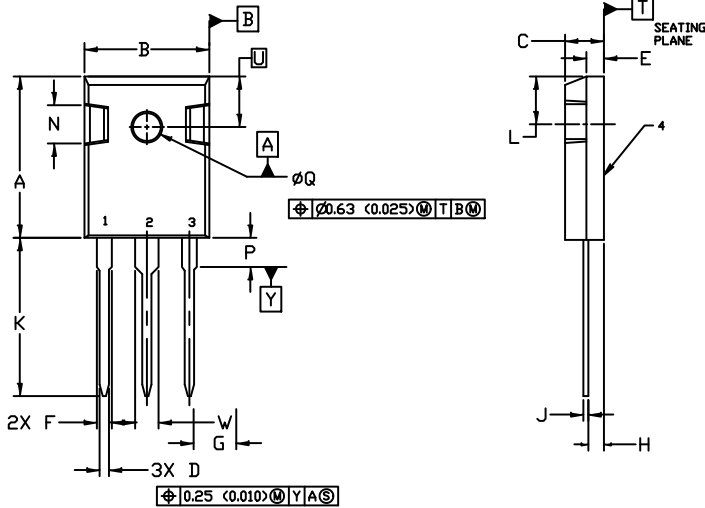
MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



TO-247
CASE 340L
ISSUE G

DATE 06 OCT 2021

SCALE 1:1

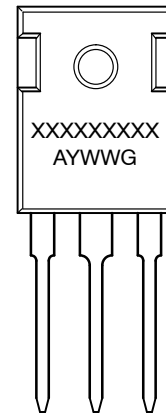


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER

DIM	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	20.32	21.08	0.800	0.830
B	15.75	16.26	0.620	0.640
C	4.70	5.30	0.185	0.209
D	1.00	1.40	0.040	0.055
E	1.90	2.60	0.075	0.102
F	1.65	2.13	0.065	0.084
G	5.45 BSC		0.215 BSC	
H	1.50	2.49	0.059	0.098
J	0.40	0.80	0.016	0.031
K	19.81	20.83	0.780	0.820
L	5.40	6.20	0.212	0.244
N	4.32	5.49	0.170	0.216
P	----	4.50	----	0.177
Q	3.55	3.65	0.140	0.144
U	6.15 BSC		0.242 BSC	
W	2.87	3.12	0.113	0.123

GENERIC
MARKING DIAGRAM*



- | | | | |
|--|--|--|--|
| <p>STYLE 1:
PIN 1. GATE
2. DRAIN
3. SOURCE
4. DRAIN</p> | <p>STYLE 2:
PIN 1. ANODE
2. CATHODE (S)
3. ANODE 2
4. CATHODES (S)</p> | <p>STYLE 3:
PIN 1. BASE
2. COLLECTOR
3. EMITTER
4. COLLECTOR</p> | <p>STYLE 4:
PIN 1. GATE
2. COLLECTOR
3. EMITTER
4. COLLECTOR</p> |
| <p>STYLE 5:
PIN 1. CATHODE
2. ANODE
3. GATE
4. ANODE</p> | <p>STYLE 6:
PIN 1. MAIN TERMINAL 1
2. MAIN TERMINAL 2
3. GATE
4. MAIN TERMINAL 2</p> | | |

- XXXXX = Specific Device Code
A = Assembly Location
Y = Year
WW = Work Week
G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

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